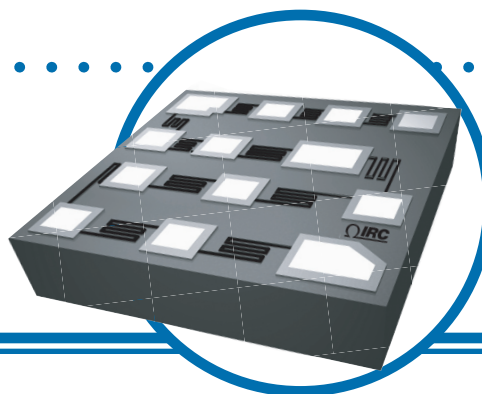


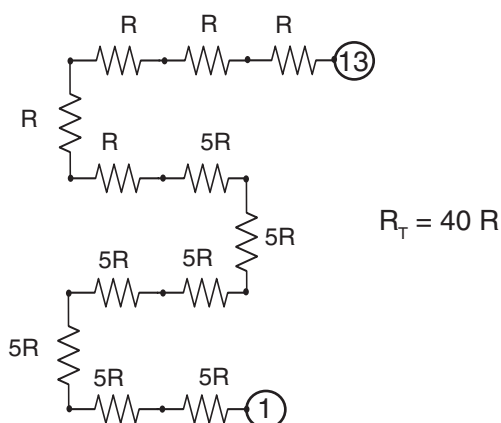
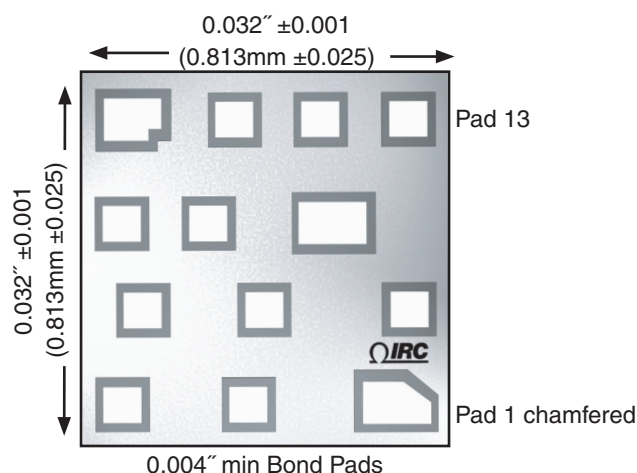
Wire Bondable Multi-tap Chip Resistors

WBC Series

- High resistor density
- MIL inspection available
- Multi-tapped chip resistor



Physical Data



Electrical Data

Absolute Tolerance	to $\pm 5\%$	
Absolute TCR	to $\pm 25 \text{ppm}/^\circ\text{C}$	
Package Power Rating (@ 70°C)	250mW	
Rated Operating Voltage (not to exceed $\sqrt{P \times R}$)	100V	
Operating Temperature	-55°C to $+150^\circ\text{C}$	
Noise	< -30dB	
Substrate Material	Oxidized Silicon (10KÅ SiO ₂ minimum)	
Substrate Thickness	0.010" $\pm$ 0.001 (0.254mm $\pm$ 0.025)	
Bond Pad Metallization	Aluminum	10KÅ minimum
	Gold	15KÅ minimum
Backside	Silicon (gold available)	
Passivation	Silicon Dioxide or Silicon Nitride	

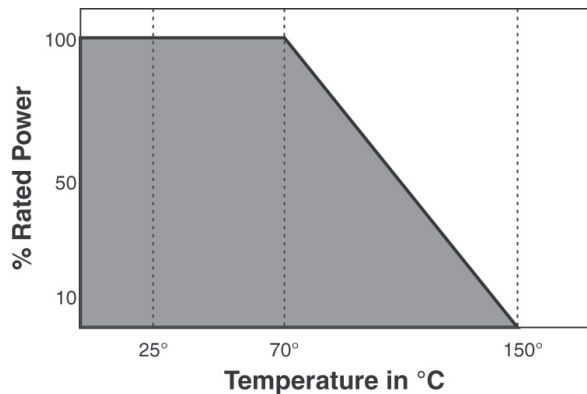
General Note

IRC reserves the right to make changes in product specification without notice or liability.
All information is subject to IRC's own data and is considered accurate at time of going to print.

Wire Bondable Multi-tap Chip Resistors



Power Derating Data



TCR/Inspection Code Table

Absolute TCR	Commercial Code	MIL Inspection Code*
$\pm 300\text{ppm}/^{\circ}\text{C}$	00	04
$\pm 100\text{ppm}/^{\circ}\text{C}$	01	05
$\pm 50\text{ppm}/^{\circ}\text{C}$	02	06
$\pm 25\text{ppm}/^{\circ}\text{C}$	03	07

*Notes: Product supplied to Class H of MIL-PRF 38534 include 100% visual inspection

Environmental Data

Test	Method	Max ΔR	Typical ΔR
Thermal Shock	MIL-STD-202 Method 107 Test condition F	$\pm 0.1\%$	$\pm 0.02\%$
High Temperature Exposure	MIL-STD-883 Method 1008 150°C, 1000 hours	$\pm 0.1\%$	$\pm 0.05\%$
Low Temperature Storage	-55°C, 1000 hours	$\pm 0.03\%$	$\pm 0.01\%$
Life	MIL-STD-202 Method 108 70°C, 1000 hours	$\pm 0.5\%$	$\pm 0.01\%$
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	$\pm 0.5\%$	$\pm 0.05\%$

Wire Bondable Multi-tap Chip Resistors



Manufacturing Capabilities Data

Resistance R Total	Available Absolute Tolerances	Best Absolute TCR
100Ω	M K	±100ppm/°C
400Ω	M K J	±100ppm/°C
800Ω	M K J	±100ppm/°C
2.4KΩ	M K J	±50ppm/°C
8.0KΩ	M K J	±50ppm/°C
24KΩ	M K J	±25ppm/°C
80KΩ	M K J	±25ppm/°C

Ordering Data

Prefix	WBC	-	M0303	A	S	-	01	-	2402	-	J
Style	M0303										
Bonding pads											
A = Aluminum; G = Gold											
Backside											
G = Gold; S = Silicon											
TCR/Inspection Code											
Reference TCR/Inspection Code Table											
Total Resistance = R_T											
4-Digit Resistance Code											
Ex: 8000 = 800Ω; 2402 = 24.0KΩ											
Reference manufacturing Capabilities Data Table for available resistances											
Absolute Tolerance Code											
M = ±20%; K = ±10%; J = ±5%											

Packaging

Standard packaging is 2" x 2" chip tray. For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.